

650V N-Channel Super-Junction MOSFET Gen-II

Description

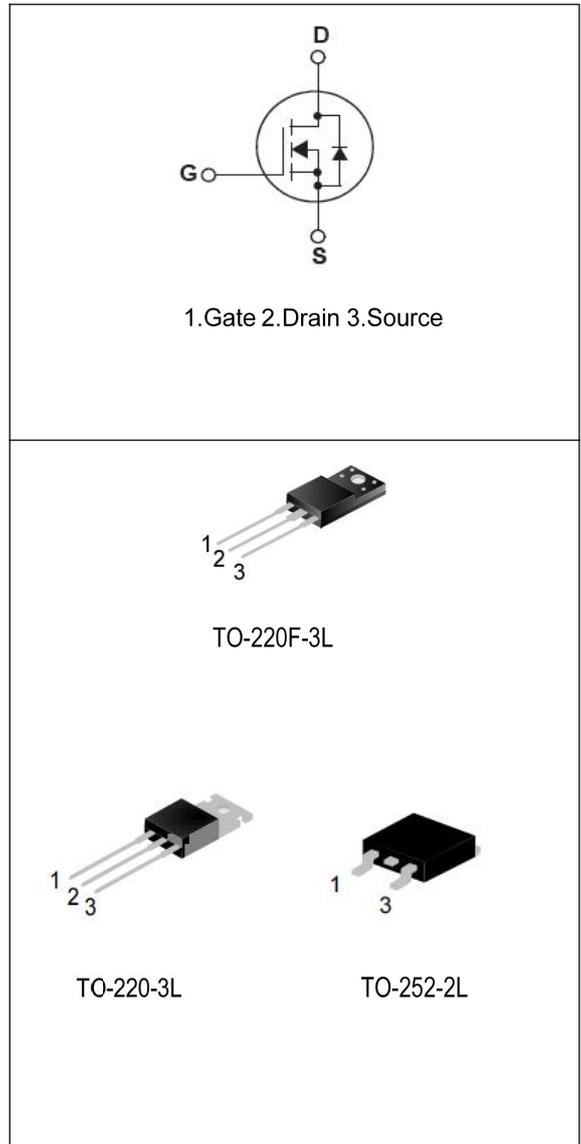
SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy.

SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

Features

- Multi-Epi process SJ-FET
- 700V@T_J=150°C
- Typ. R_{DS(on)}=0.55Ω
- Ultra Low Gate Charge (typ. Q_g=13.6nC)
- 100% avalanche t_{setd}



Package Marking and Ordering Information:

| Marking | Package | Part # | Hazardous Substance Control | Packing |
|-----------|------------|-----------|-----------------------------|---------|
| SR65R650F | T0-220F-3L | SR65R650F | Pb free | Tube |
| SR65R650T | T0-220-3L | SR65R650T | Pb free | Tube |
| SR65R650D | TO-252-2L | SR65R650D | Halogen free | Reel |

Absolute Maximum Ratings

| Symbol | Parameter | SR65R650T/D | SR65R650F | Unit |
|----------|---|-------------|-----------|------|
| VDSS | Drain-Source Voltage | 650 | | V |
| ID | Drain Current-Continuous(TC=25°C) | 7.8* | | A |
| | -Continuous(TC=100°C) | 4.9* | | |
| IDM | Drain Current-Pulsed(Note1) | 31.2* | | A |
| VGSS | Gate-Source Voltage | ±30 | | V |
| EAS | Single Pulsed Avalanche Energy(Note2) | 106 | | mJ |
| IAS | Avalanche current,repitive or not-repitive (pulse width limited by Tj max) | 2.7 | | A |
| DV/DT | Peak Diode Recovery DV/DT(Note3) | 15 | | V/ns |
| DV/DS/DT | Drain Source Voltage Slope(Vds=640V) | 50 | | V/ns |
| PD | Power Dissipation(TC=25°C) | 80 | 30 | W |
| TJ,TSTG | Operating and Storage Temperature Range | -55to+150 | | °C |
| TL | Maximun Lead Temperature for Soldring Purpose,1/8"from Case for 5 Seconds | 260 | | °C |

* Drain current limited by maximum junction temperature . Maximum duty cycle D=0.75.

Thermal Characteristics

| Symbol | Parameter | SR65R650T/D | SR65R650F | Unit |
|--------|--|-------------|-----------|------|
| RθJC | Thermal Resistance,Junction-to-Case | 1.55 | 4.2 | °C/W |
| RθCS | Thermal Resistance,Case-to-Sink Typ | 0.5 | - | °C/W |
| RθJA | Thermal Resistance,Junction-to-Ambient | 62 | 80 | °C/W |

Electrical Characteristics TC = 25°C unless otherwise noted

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|-----|------|----------|----------|
| Off Characteristics | | | | | | |
| BVDSS | Drain-Source Breakdown Voltage | VGS=0V, ID=250uA Tj=25°C | 650 | - | - | V |
| | | VGS=0V, ID=250uA Tj=150°C | - | 700 | - | V |
| BVDSS/TJ | Breakdown Voltage Temperature Coefficient | ID=250uA, Referenced to 25°C | - | 0.6 | - | V/°C |
| IDSS | Zero Gate Voltage Drain Current | VDS=650V, VGS=0V TC=125°C | - | - | 1 100 | uA uA |
| IGSSF | Gate-Body Leakage Current, Forward | VGS=30V, VDS=0V | - | - | 100 | nA |
| IGSSR | Gate-Body Leakage Current, Reverse | VGS=-30V, VDS=0V | - | - | -100 | nA |
| On Characteristics | | | | | | |
| VGS(th) | Gate Threshold Voltage | VDS=VGS, ID=250uA | 2.0 | 3.0 | 4.0 | V |
| Rg | Gate resistance | f=1MHz, open drain | - | 9.6 | - | Ω |
| RDS(on) | Static Drain-Source On-Resistance | VGS=10V, ID=3.5A (TO-220/TO-220F) | - | 0.55 | 0.65 | Ω |
| | | VGS=10V, ID=3.5A (TO-252) | - | 0.56 | 0.67 | Ω |
| Dynamic Characteristics | | | | | | |
| Ciss | Input Capacitance | VDS=100V, VGS=0V, f=1.0MHz | - | 480 | - | pF |
| Coss | Output Capacitance | | - | 22 | - | pF |
| Crss | Reverse Transfer Capacitance | | - | 1.1 | - | pF |
| Switching Characteristics | | | | | | |
| td(on) | Turn-On Delay Time | VDS=400V, ID=3.9A RG=10Q, VGS=10V (Note4) | - | 11 | - | ns |
| tr | Turn-On Rise Time | | - | 21 | - | ns |
| td(off) | Turn-Off Delay Time | | - | 40 | - | ns |
| tf | Turn-Off Fall Time | | - | 31 | - | ns |
| Qg | Total Gate Charge | VDS=400V, ID=7.8A VGS=10V, (Note4) | - | 13.6 | - | nc |
| Qgs | Gate-Source Charge | | - | 3.2 | - | nc |
| Qgd | Gate-Drain Charge | | - | 5.6 | - | nc |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| IS | Maximum Continuous Drain-Source Diode Forward Current | | - | - | 7.8 | A |
| ISM | Maximum Pulsed Drain-Source Diode Forward Current | | - | - | 31.2 | A |
| VSD | Drain-Source Diode Forward voltage | VGS=0V, IS=7.8A | - | 0.9 | 1.4 | V |
| Trr | Reverse Recovery Time | VGS=0V, VDS=400V, IS=3.9A, dIF/dt=100A/us | - | 205 | - | ns |
| Qrr | Reverse Recovery Charge | | - | 1.4 | - | uC |
| Irrm | Peak Reverse Recovery Current | | - | 12 | - | A |

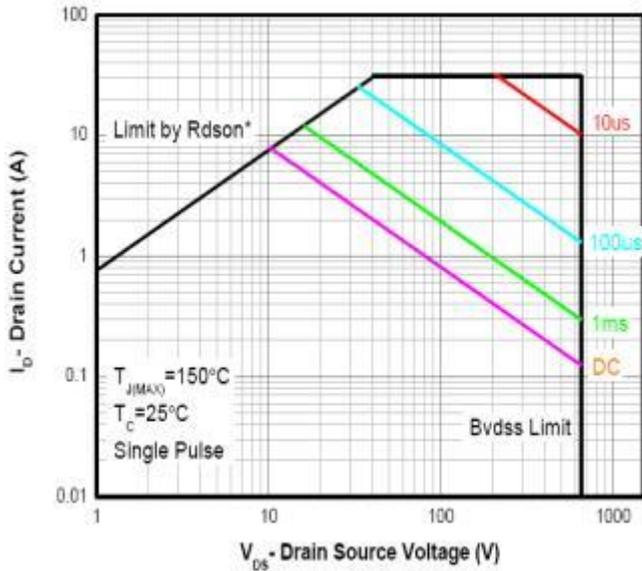
NOTES:

- 1.Repetitive Rating:Pulse width limited by maximum junction temperature.
- 2.ID=IAS,VDD=50V,Starting TJ=25°C.
- 3.ISD≤ID,di/dt≤200A/us,VDD≤BVDSS,Starting TJ=25°C.
- 4.Essentially Independent of Operating Temperature Typical Characteristics.

Typical Performance Characteristics

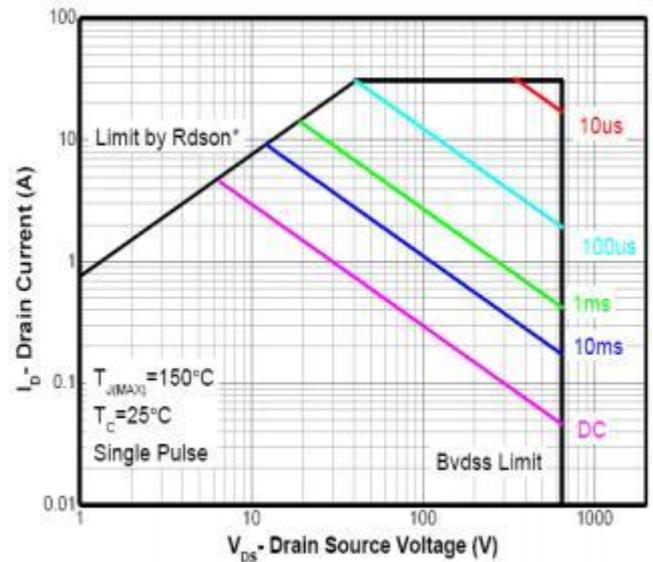
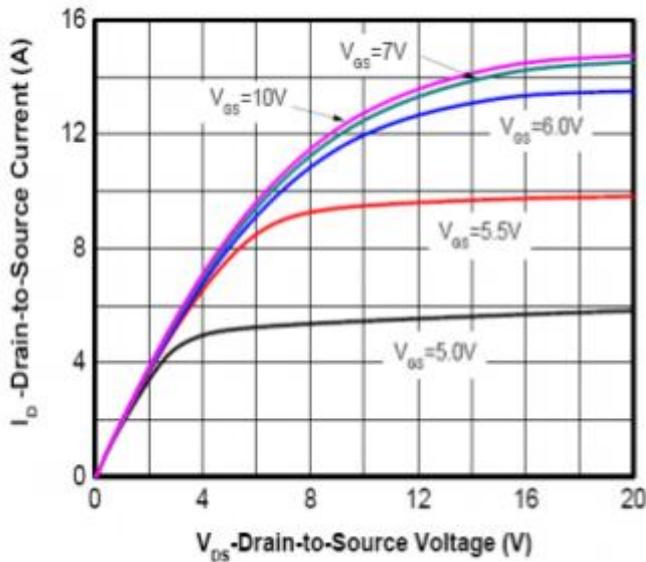
Safe operating area TC=25°C

TO-220.TO-252

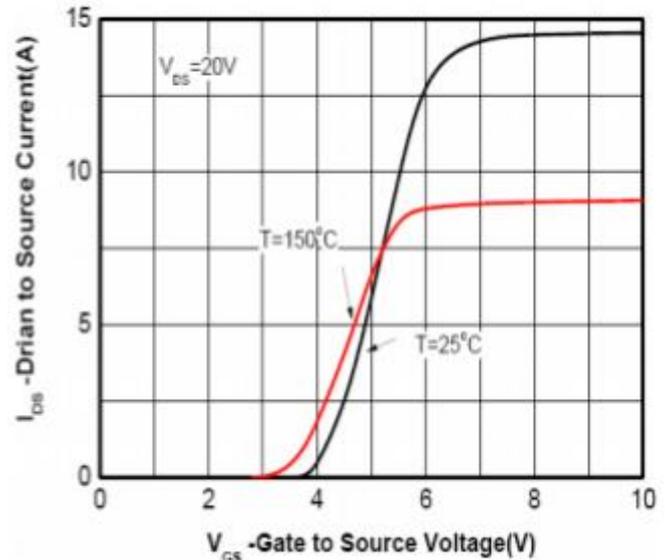


Safe operating area TC=25°C

TO-220FullPAK

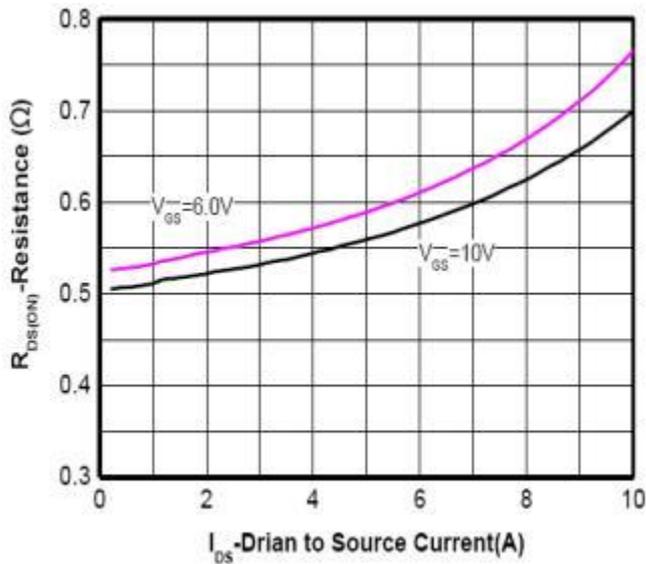

 Typ.output characteristics $T_j=25^\circ\text{C}$


Typ. transfer characteristics

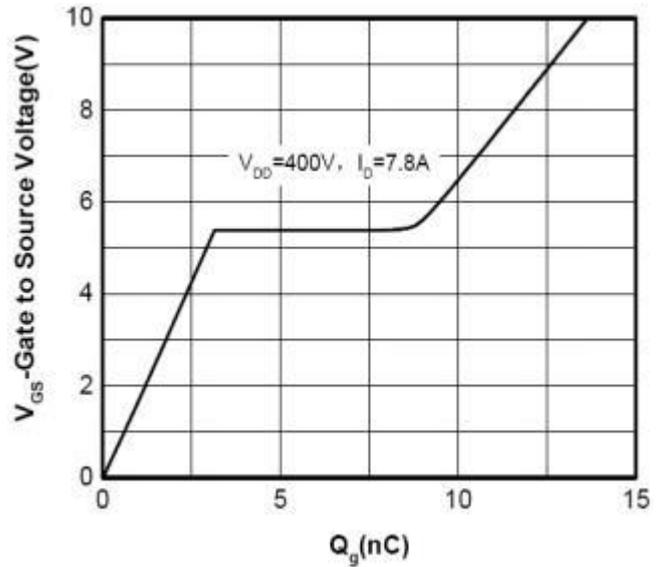


Typical Performance Characteristics

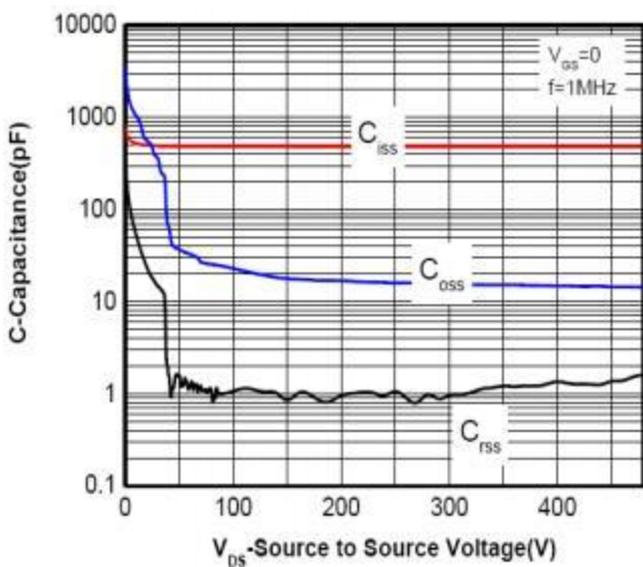
Typ. Drain-source on-state resistance



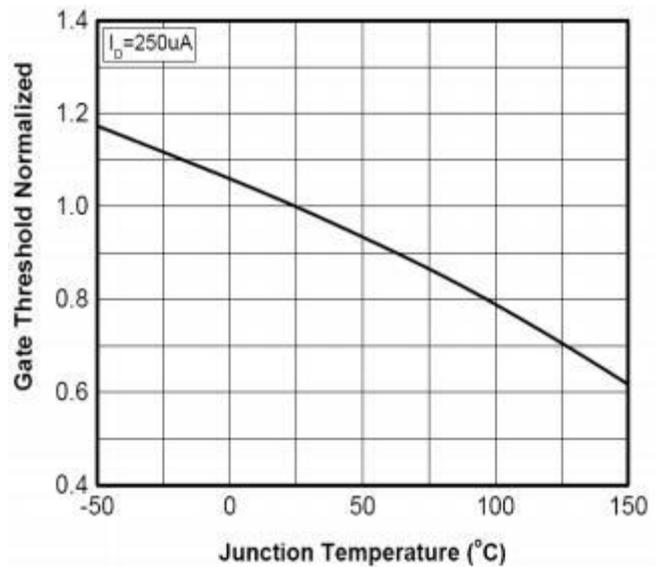
Typ. gate charge characteristics



Typ. capacitances

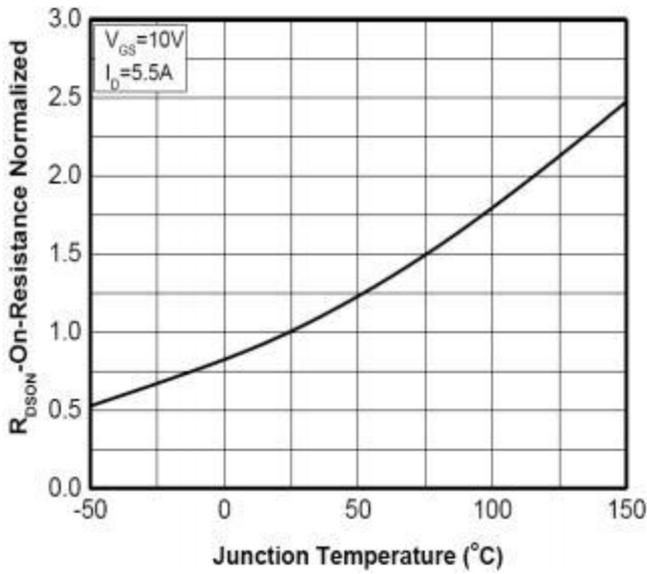


Normalized VGS(th) characteristics

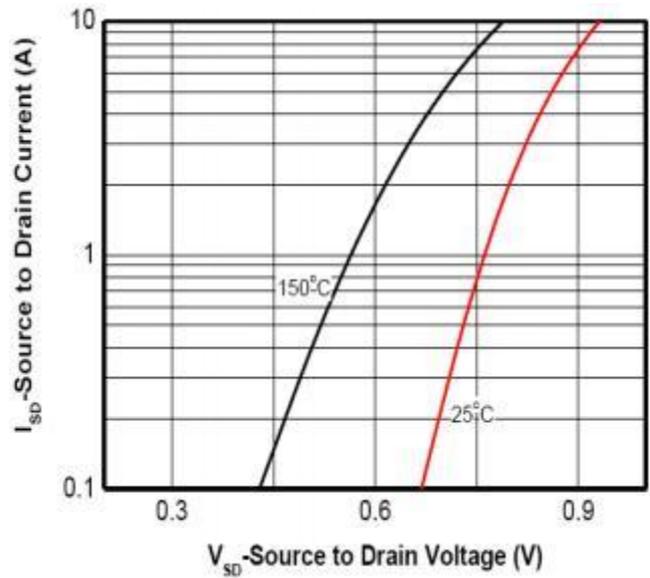


Typical Performance Characteristics

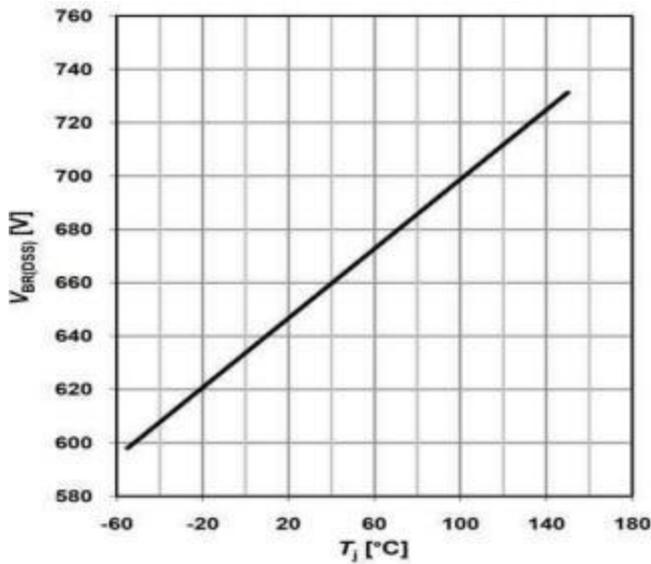
Normalized on-resistance vs temperature



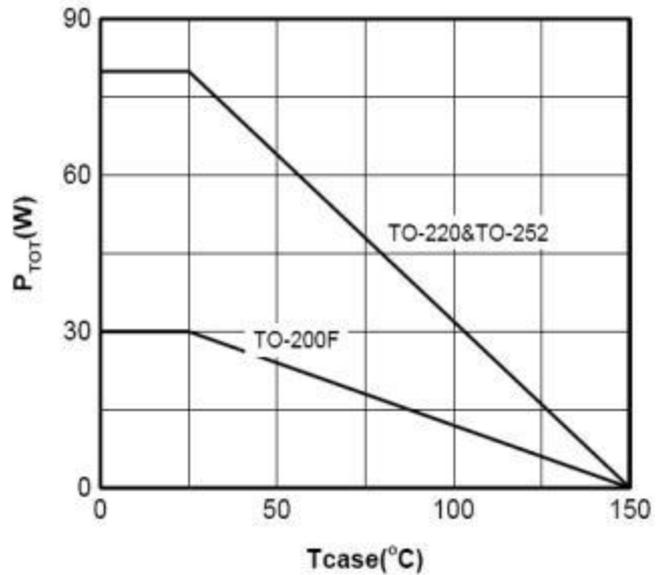
Forward characteristics of reverse diode



Drain-source breakdown voltage



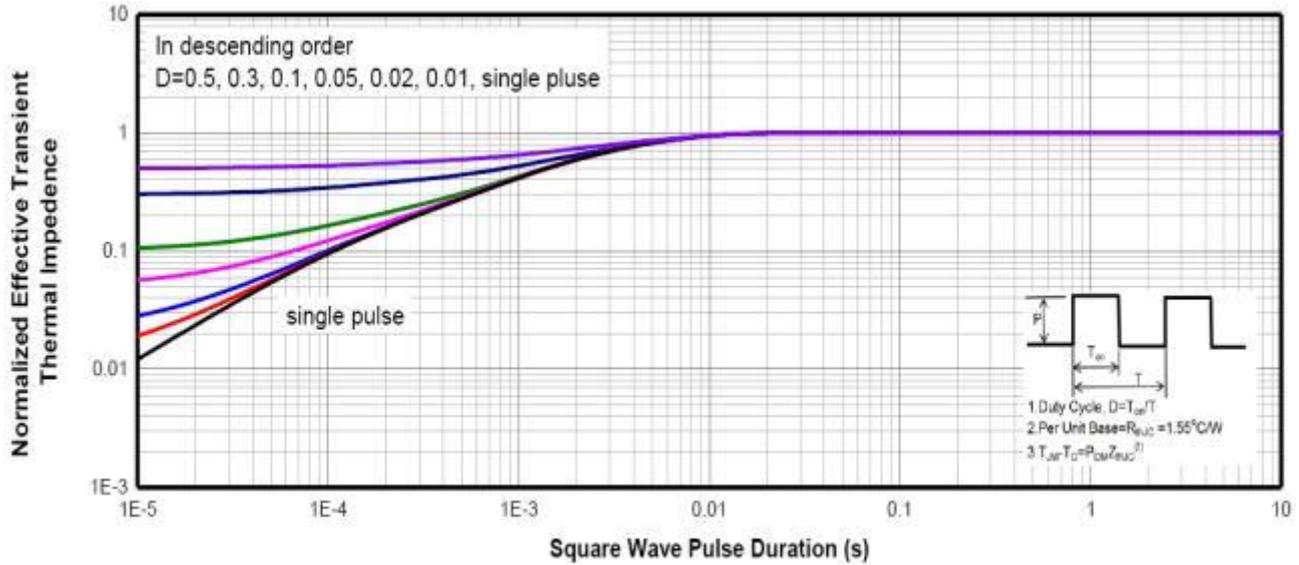
Power dissipation



Typical Performance Characteristics

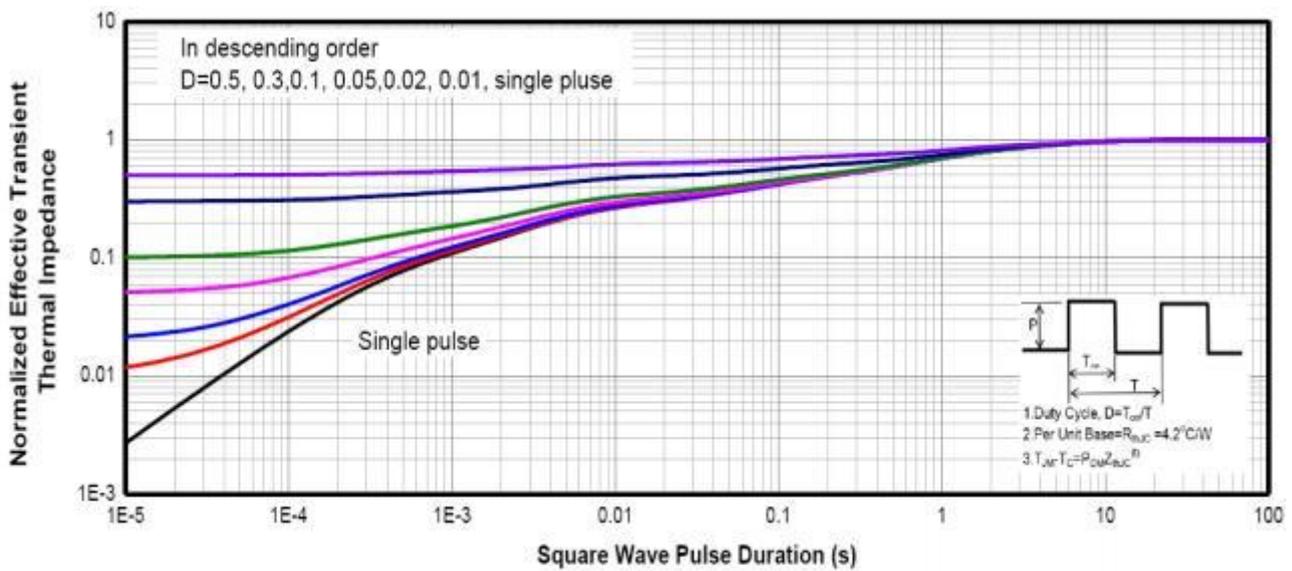
Max. transient thermal impedance

TO-220,TO-252



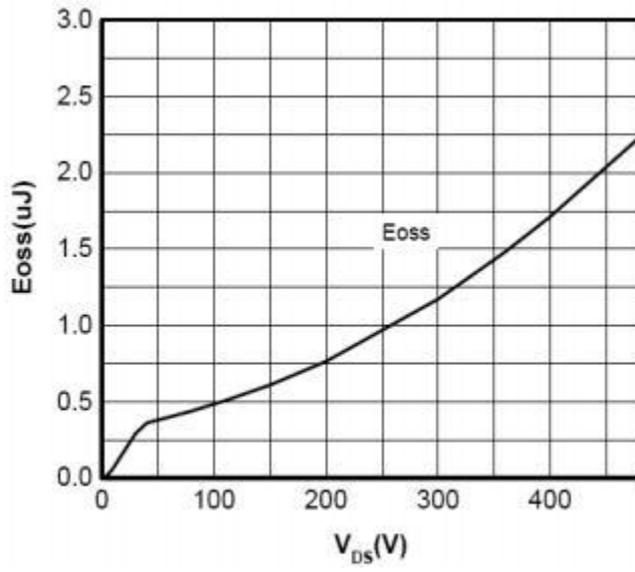
Max. transient thermal impedance

TO-220FullPAK



Typical Performance Characteristics

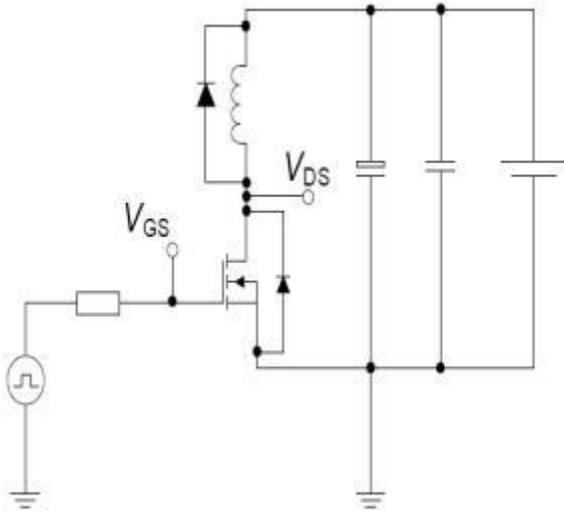
Coss stored energy



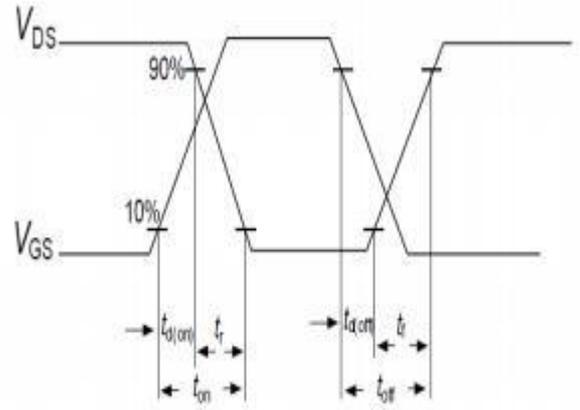
Test circuits

Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

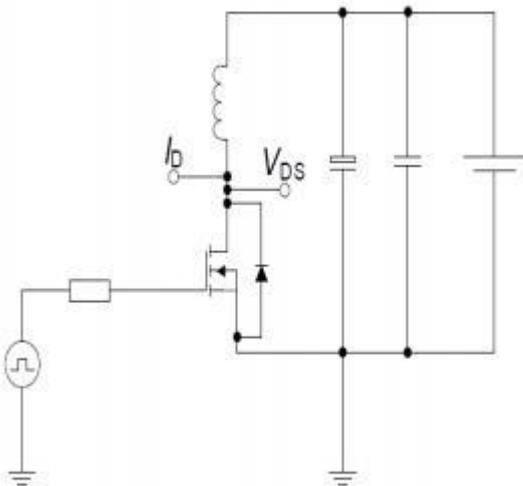


Switching time waveform

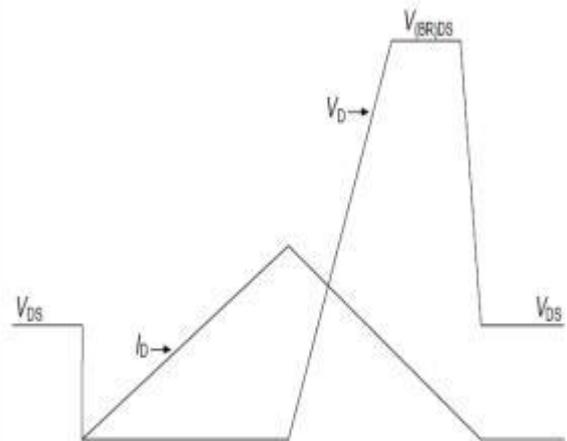


Unclamped inductive load test circuit waveform

Unclamped inductive load test circuit



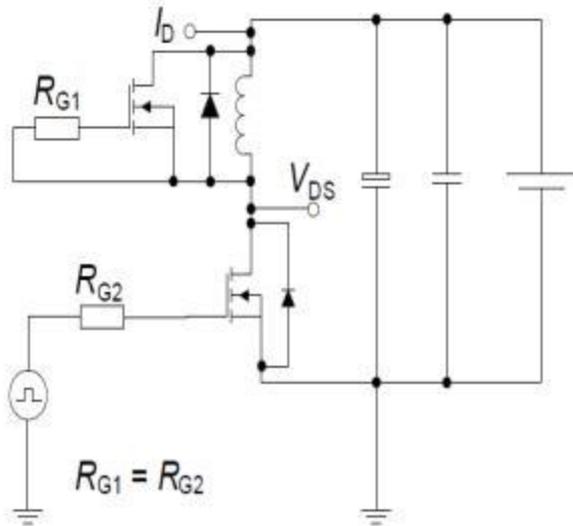
Unclamped inductive waveform



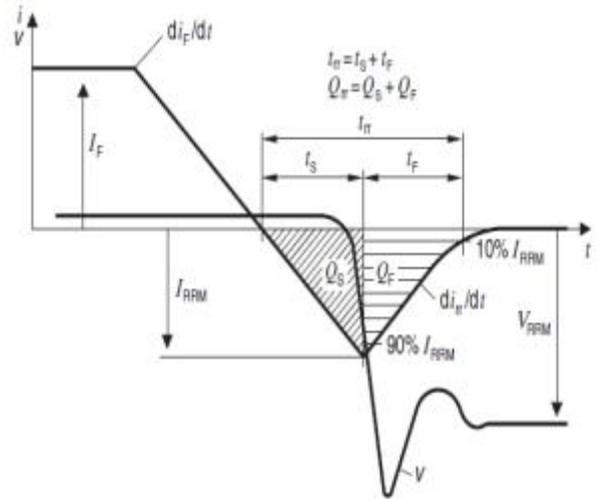
Test circuits

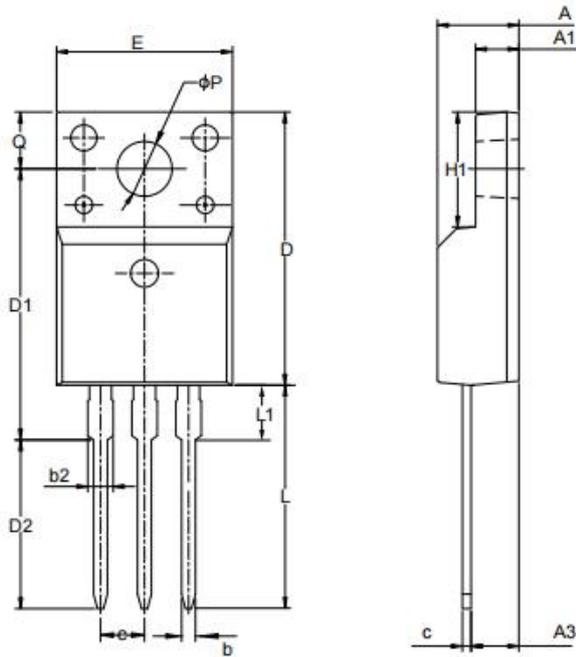
Test circuit and waveform for diode characteristics

Test circuit for diode characteristics

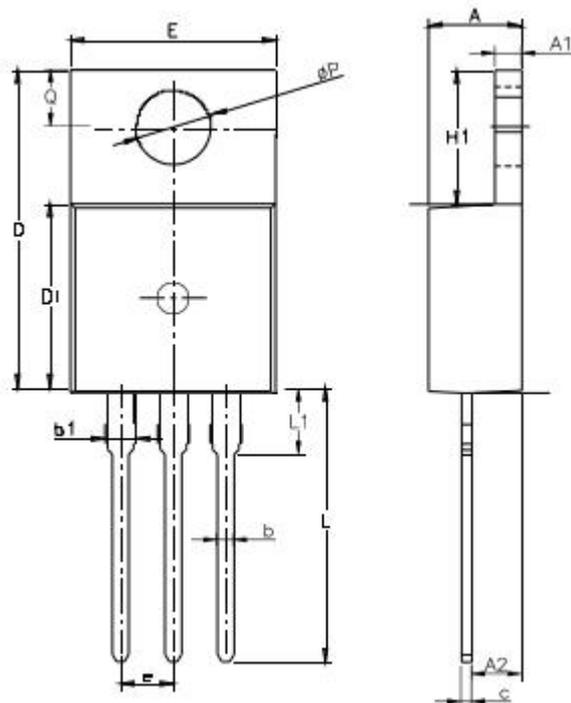


Diode recovery waveform



Package Outline
TO-220 Full PAK


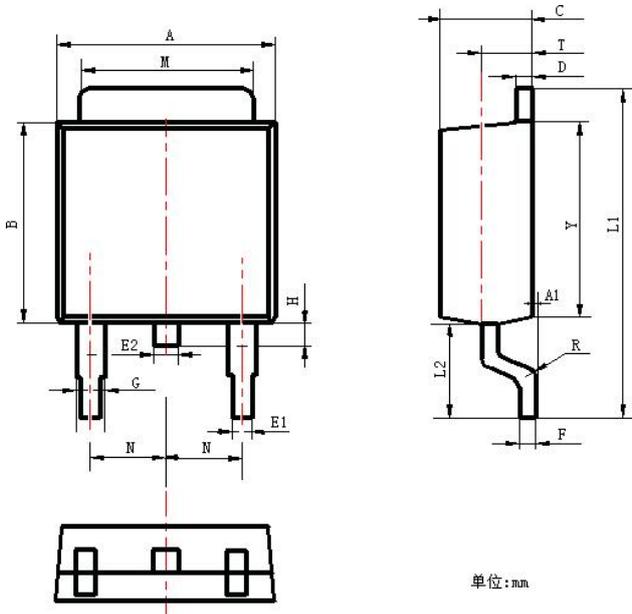
| COMMON DIMENSIONS | | | |
|-------------------|------------|-------|-------|
| Items | Values(mm) | | |
| | MIN | NOM | MAX |
| A | 4.42 | 4.7 | 5.02 |
| A1 | 2.3 | 2.54 | 2.8 |
| A3 | 2.5 | 2.76 | 3.1 |
| b | 0.7 | 0.8 | 0.9 |
| b2 | -- | -- | 1.47 |
| c | 0.35 | 0.5 | 0.65 |
| D | 15.25 | 15.87 | 16.25 |
| D1 | 15.3 | 15.75 | 16.3 |
| D2 | 9.3 | 9.8 | 10.3 |
| E | 9.73 | 10.16 | 10.36 |
| e | 2.54BSC | | |
| H1 | 6.4 | 6.68 | 7 |
| L | 12.48 | 12.98 | 13.48 |
| L1 | -- | -- | 3.5 |
| ϕP | 3 | 3.18 | 3.4 |
| Q | 3.05 | 3.3 | 3.55 |

TO-220-3L


| COMMON DIMENSIONS | | | |
|-------------------|------------|-------|------|
| Items | Values(mm) | | |
| | MIN | NOM | MAX |
| A | 4.3 | 4.5 | 4.7 |
| A1 | 1 | 1.3 | 1.5 |
| A2 | 1.8 | 2.4 | 2.8 |
| b | 0.6 | 0.8 | 1 |
| b1 | 1 | - | 1.6 |
| c | 0.3 | - | 0.7 |
| D | 15.1 | 15.7 | 16.1 |
| D1 | 8.1 | 9.2 | 10 |
| F | 9.6 | 9.9 | 10.4 |
| e | 2.54BSC | | |
| H1 | 6.1 | 6.5 | 7 |
| L | 12.6 | 13.08 | 13.6 |
| L1 | | | 3.95 |
| ϕP | 3.4 | 3.7 | 3.9 |
| Q | 2.6 | | 3.2 |

Package Outline

TO-252-2L



单位: mm

| COMMON DIMENSIONS | | | |
|-------------------|------------|------|------|
| Items | Values(mm) | | |
| | MIN | NOW | MAX |
| A | 6.3 | 6.5 | 6.9 |
| A1 | 0 | - | 0.16 |
| B | 5.7 | - | 6.3 |
| C | 2.1 | 2.3 | 2.5 |
| D | 0.3 | 0.5 | 0.7 |
| E1 | 0.6 | 0.65 | 0.9 |
| E2 | 0.7 | 0.65 | 1 |
| F | 0.3 | 0.5 | 0.6 |
| G | 0.7 | 0.9 | 1.2 |
| L1 | 9.6 | 10 | 10.5 |
| L2 | 2.7 | - | 3.1 |
| H | 0.4 | - | 1 |
| M | 5.1 | 5.2 | 5.5 |
| N | 2.09 | 2.2 | 2.49 |
| R | 0.3 | | |
| T | 1.4 | - | 1.6 |
| Y | 5.1 | 5.9 | 6.3 |